

High Speed Infrared Emitting Diode, 940 nm, Surface Emitter Technology



LINKS TO ADDITIONAL RESOURCES



DESCRIPTION

As part of the [SurfLight™](#) portfolio, the VSMY2943SLX01 is an infrared, 940 nm, side looking emitting diode based on GaAlAs surface emitter chip technology with extreme high radiant intensities, high optical power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

FEATURES

- Package type: surface-mount
- Package form: side view
- Dimensions (L x W x H in mm): 2.3 x 2.55 x 2.3
- AEC-Q101 qualified
- Peak wavelength: $\lambda_p = 940$ nm
- High reliability
- High radiant power
- Very high radiant intensity
- Angle of half intensity: $\phi = \pm 28^\circ$
- Suitable for high pulse current operation
- Package matches with detector VEMD2xx3SLX01 and VEMT2xx3SLX01 series
- Floor life: 4 weeks, MSL 2a, acc. J-STD-020
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

AUTOMOTIVE
GRADE

RoHS
COMPLIANT
HALOGEN
FREE
GREEN
(5-2008)

APPLICATIONS

- Automotive sensor
- Photointerrupters
- Optical switch
- Emitter source for proximity sensors
- IR illumination
- Remote control
- [Head-up displays](#)

PRODUCT SUMMARY

COMPONENT	I_e (mW/sr)	ϕ (°)	λ_p (nm)	t_r (ns)
VSMY2943SLX01	50	± 28	940	10

Note

- Test conditions see table “Basic Characteristics”

ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMY2943SLX01	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	Side view

Note

- MOQ: minimum order quantity

**ABSOLUTE MAXIMUM RATINGS** ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V_R	5	V
Forward current		I_F	100	mA
Peak forward current	$t_p/T = 0.5$, $t_p = 100\text{ }\mu\text{s}$	I_{FM}	200	mA
Surge forward current	$t_p = 100\text{ }\mu\text{s}$	I_{FSM}	1	A
Power dissipation		P_V	180	mW
Junction temperature		T_j	100	$^{\circ}\text{C}$
Operating temperature range		T_{amb}	-40 to +85	$^{\circ}\text{C}$
Storage temperature range		T_{stg}	-40 to +100	$^{\circ}\text{C}$
Soldering temperature	According to Fig. 7, J-STD-020	T_{sd}	260	$^{\circ}\text{C}$
Thermal resistance junction to ambient	J-STD-051, soldered on PCB	R_{thJA}	250	K/W

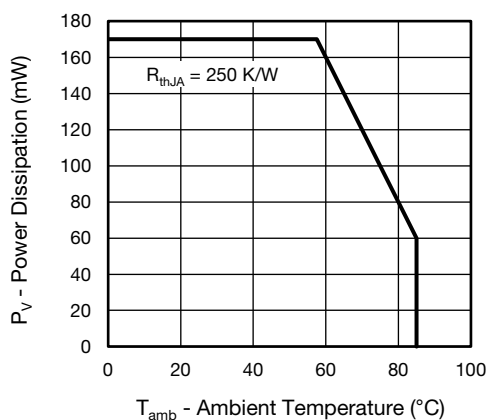


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

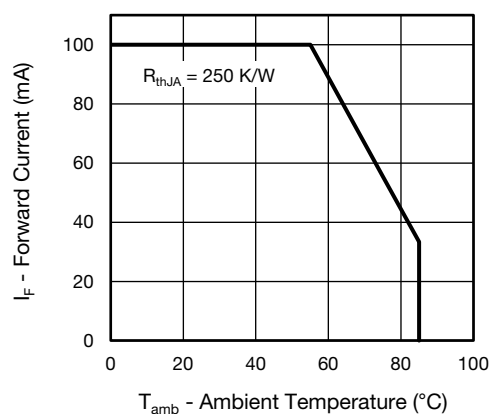


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$	V_F	-	1.4	1.8	V
	$I_F = 1\text{ A}$, $t_p = 100\text{ }\mu\text{s}$	V_F	-	2.5	-	V
Temperature coefficient of V_F	$I_F = 100\text{ mA}$	TK_{VF}	-	-0.7	-	mV/K
Reverse current		I_R	not designed for reverse operation			μA
Junction capacitance	$V_R = 0\text{ V}$, $f = 1\text{ MHz}$, $E = 0\text{ mW/cm}^2$	C_J	-	55	-	pF
Radiant intensity	$I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$	I_e	27	50	75	mW/sr
	$I_F = 1\text{ A}$, $t_p = 100\text{ }\mu\text{s}$	I_e	-	350	-	mW/sr
Radiant power	$I_F = 100\text{ mA}$, $t_p = 20\text{ ms}$	ϕ_e	-	55	-	mW
Temperature coefficient of radiant power	$I_F = 100\text{ mA}$	$TK\phi_e$	-	-0.2	-	%/K
Angle of half intensity		ϕ	-	± 28	-	$^{\circ}$
Peak wavelength	$I_F = 100\text{ mA}$	λ_p	920	940	960	nm
Spectral bandwidth	$I_F = 100\text{ mA}$	$\Delta\lambda$	-	50	-	nm
Temperature coefficient of λ_p	$I_F = 100\text{ mA}$	$TK\lambda_p$	-	0.25	-	nm/K
Rise time	$I_F = 100\text{ mA}$, 10 % to 90 %	t_r	-	10	-	ns
Fall time	$I_F = 100\text{ mA}$, 10 % to 90 %	t_f	-	10	-	ns

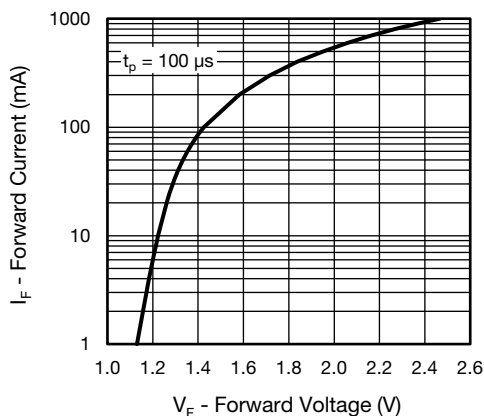
BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)


Fig. 3 - Forward Current vs. Forward Voltage

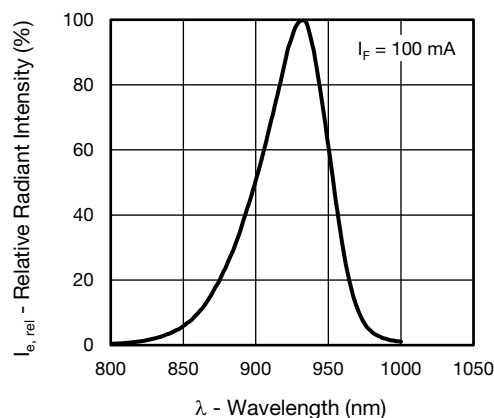


Fig. 5 - Relative Radiant Intensity vs. Wavelength

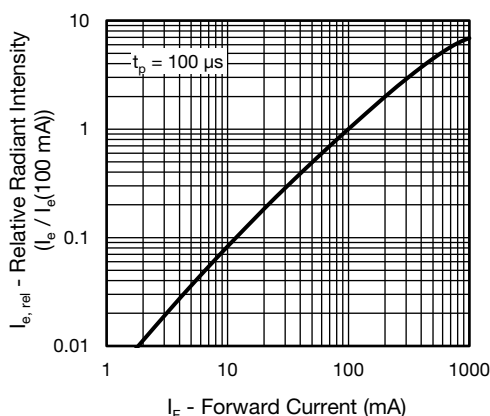
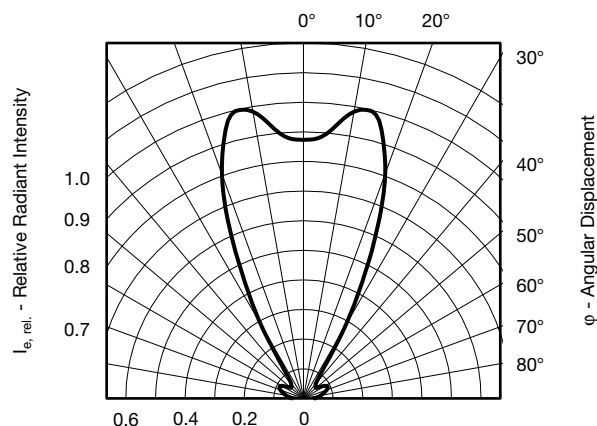
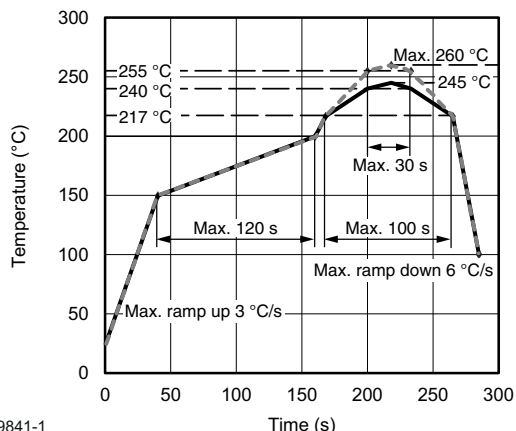


Fig. 4 - Relative Radiant Intensity vs. Forward Current



22688-1

Fig. 6 - Relative Radiant Intensity vs. Angular Displacement

SOLDER PROFILE


19841-1

Fig. 7 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

Conditions: $T_{amb} < 30\text{ }^{\circ}\text{C}$, RH < 60 %

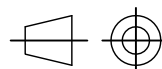
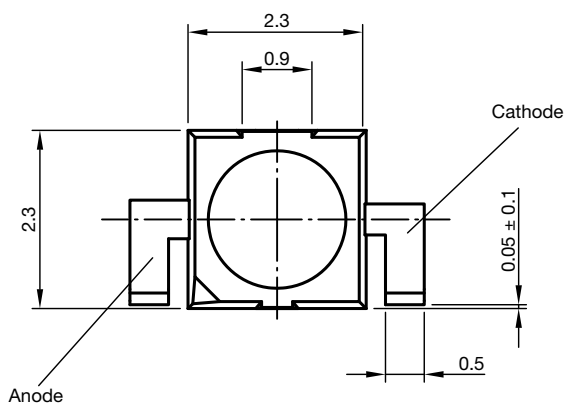
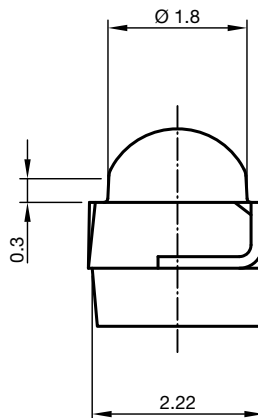
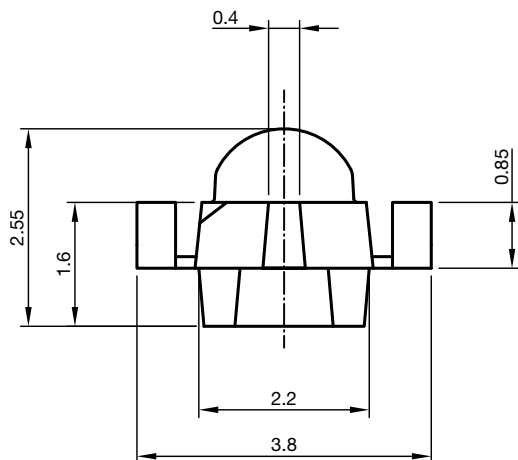
Moisture sensitivity level 2a, according to J-STD-020.

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at $40\text{ }^{\circ}\text{C}$ (+ 5 °C), RH < 5 %.



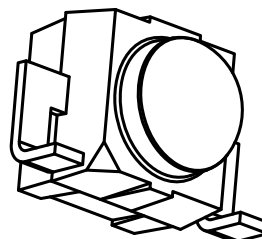
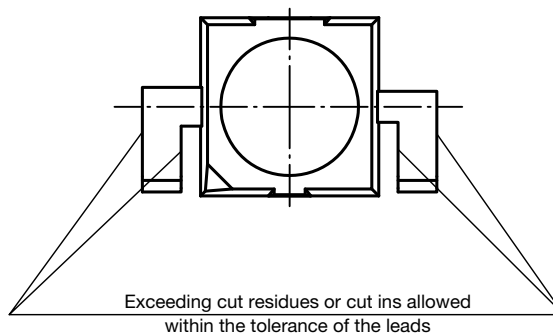
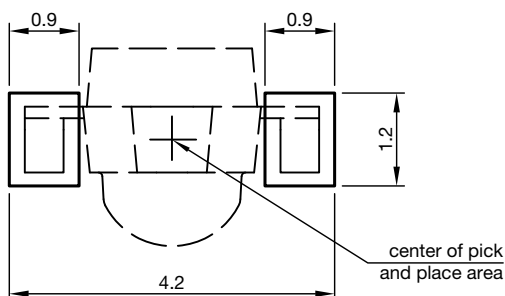
PACKAGE DIMENSIONS in millimeters



Technical drawings
according to DIN
specifications

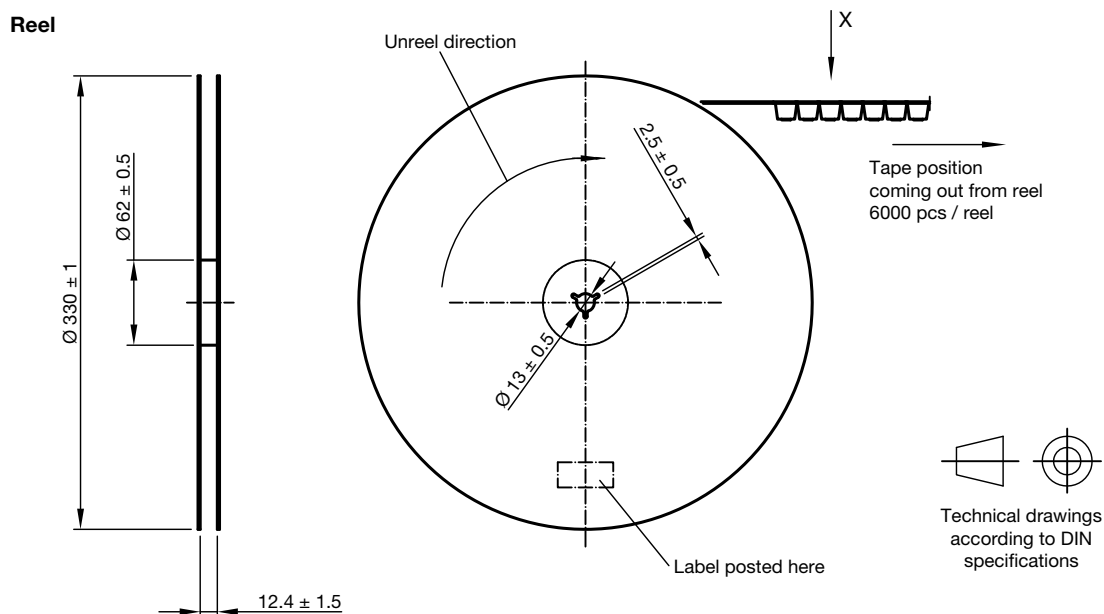
Not indicated tolerances ± 0.2

Solder pad proposal
acc. IPC 7351

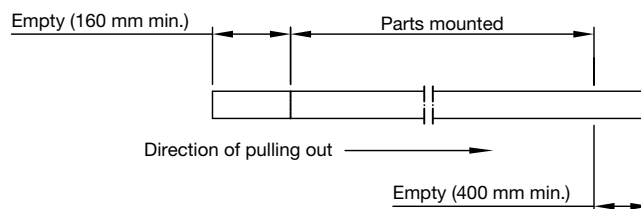


Drawing-No.: 6.544-5410.03-4
Issue: 3; 02.10.15

TAPING AND REEL DIMENSIONS in millimeters

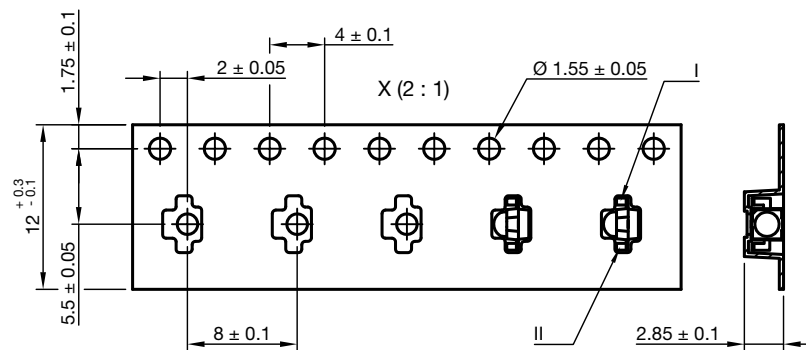


Leader and trailer tape



Terminal position in tape

Device	Lead I	Lead II
VSMB2943SLX01	Cathode	Anode
VSMF2893SLX01		
VSMB2948SL		
VEMD2023SLX01		
VEMD2523SLX01		
VEMT2023SLX01	Collector	Emitter
VEMT2523SLX01		
VSMY2853SL	Anode	Cathode
VSMY2943SL		
VSMY294310SL		



Drawing-No.: 9.800-5123.01-4
Issue: 4; 02.10.15



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